Nch 45V 7A Power MOSFET

\/	45)/
V_{DSS}	45V
$R_{DS(on)}(Max.)$	25mΩ
I _D	±7.0A
P _D	2.0W

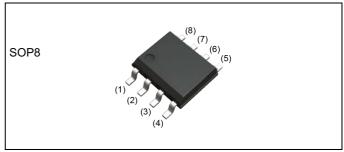
● Features

- 1) Low on-resistance
- 2) Small Surface Mount Package (SOP8)
- 3) Pb-free lead plating; RoHS compliant
- 4) Halogen Free

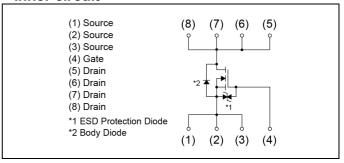
Application

Switching

Outline



●Inner circuit



Packaging specifications

i deliaging opermediation							
	Packing	Embossed Tape					
	Reel size (mm)	330					
Туре	Tape width (mm)	12					
	Basic ordering unit (pcs)	2500					
	Taping code	ТВ					
	Marking	RSH070N05					

ullet Absolute maximum ratings (T_a = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V _{DSS}	45	V
Continuous drain current	I _D	±7.0	Α
Pulsed drain current	I _{DP} *1	±28	Α
Gate - Source voltage	V_{GSS}	±20	V
Power discipation	P _D *2	2.0	W
Power dissipation	P _D *3	1.4	W
Junction temperature	T _j	150	°C
Operating junction and storage temperature range	T _{stg}	-55 to +150	°C

●Thermal resistance

Deremeter	Cumb of	Values			Lleit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal registance junction, ambient	R _{thJA} *2	-	1	62.5	°C/W
Thermal resistance, junction - ambient	R _{thJA} *3	-	1	89.2	°C/W

● Electrical characteristics (T_a = 25°C)

Parameter Symbol Conditions		Conditions	Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic	
Drain - Source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 1mA	45	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I _D = 1mA referenced to 25°C	-	46.8	-	mV/°C	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 45V, V _{GS} = 0V	-	-	1	μA	
Gate - Source leakage current	I _{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$	1	1	±10	μA	
Gate threshold voltage	$V_{GS(th)}$	V _{DS} = 10V, I _D = 1mA	1.0	1	2.5	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_{j}}$	I _D = 1mA referenced to 25°C	-	-3.9	-	mV/°C	
		V _{GS} = 10V, I _D = 7A	-	18	25		
Static drain - source on - state resistance	R _{DS(on)} *4	V _{GS} = 4.5V, I _D = 7A	-	23	32	mΩ	
		$V_{GS} = 4.0V, I_D = 7A$	-	25	35		
Gate resistance R_G $f = 1MHz$, open drain		f = 1MHz, open drain	-	3.2	1	Ω	
Forward Transfer Admittance	Y _{fs} *4	V _{DS} = 10V, I _D = 7A	6.0	-	-	S	

^{*1} Pw \leq 10 μ s, Duty cycle \leq 1%

^{*2} Mounted on a ceramic board (30×30×0.8mm)

^{*3} Mounted on a FR4 (25×25×0.8mm)

^{*4} Pulsed

●Electrical characteristics (T_a = 25°C)

Davarantari	Company of	Conditions	Values			1.1-:4	
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit	
Input capacitance	C _{iss}	V _{GS} = 0V	-	1000	-		
Output capacitance C _{oss}		V _{DS} = 10V	-	230	-	pF	
Reverse transfer capacitance	C _{rss}	f = 1MHz	1	125	1		
Turn - on delay time	t _{d(on)} *4	$V_{DD} \simeq 25V, V_{GS} = 10V$	1	16	1		
Rise time	t _r *4	I _D = 3.5A	-	27	-	no	
Turn - off delay time	t _{d(off)} *4	$R_L \simeq 7.1\Omega$		57	1	ns	
Fall time	t _f *4	$R_G = 10\Omega$	-	21	-		

• Gate charge characteristics $(T_a = 25^{\circ}C)$

	\ a	,				
Darameter	Symbol	Conditions	Values			l lm:t
Parameter		Conditions	Min.	Тур.	Max.	Unit
Total gate charge	Qg*4	V _{DD} ≃ 25V.	-	12.0	16.8	
Gate - Source charge	Q _{gs} *4	$V_{DD} \approx 25V$, $I_D = 7A$, $V_{GS} = 5V$	-	3.0	-	nC
Gate - Drain charge	Q _{gd} *4		-	4.6	-	

●Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Darameter	Symbol	Conditions	Values			l leit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Continuous forward current	I _S	T = 25°C	-	-	1.6	Α	
Pulse forward current	I _{SP} *1	T _a = 25°C	-	-	28	Α	
Forward voltage	V _{SD} *4	V _{GS} = 0V, I _S = 1.6A	-	-	1.2	V	

Fig.1 Power Dissipation Derating Curve

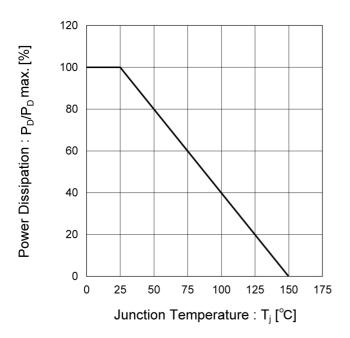
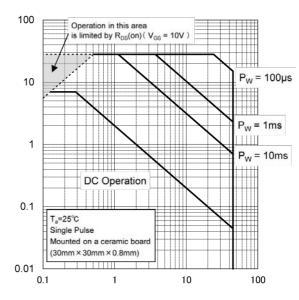


Fig.2 Maximum Safe Operating Area



Drain Current : I_D [A]

Drain - Source Voltage : V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

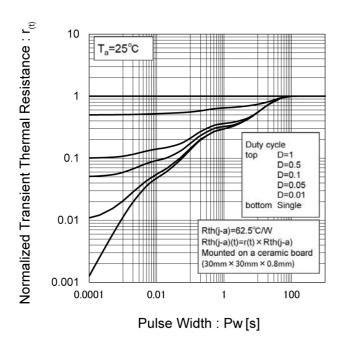
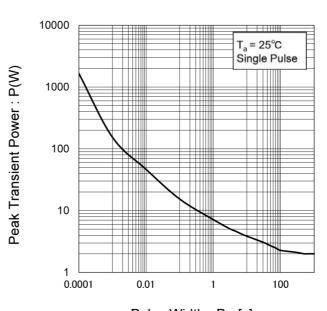


Fig.4 Single Pulse Maximum Power dissipation

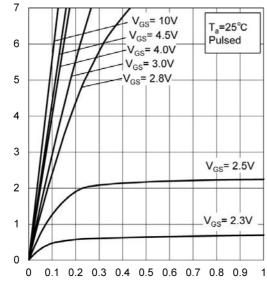


Pulse Width : Pw [s]

Drain Current : I_D [A]

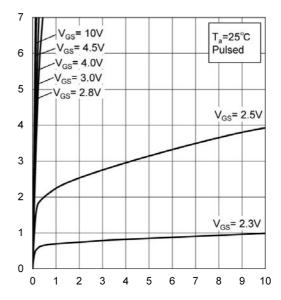
• Electrical characteristic curves

Fig.5 Typical Output Characteristics(I)



Drain - Source Voltage : V_{DS} [V]

Fig.6 Typical Output Characteristics(II)



Drain Current : I_D [A]

Drain - Source Voltage : V_{DS} [V]

Fig.7 Breakdown Voltage vs.
Junction Temperature

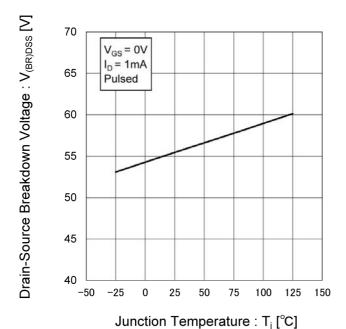


Fig.8 Typical Transfer Characteristics

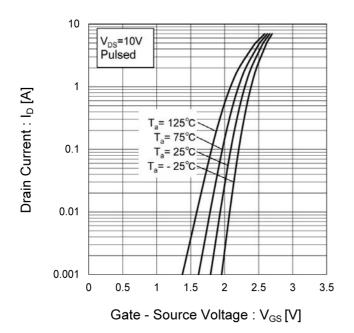
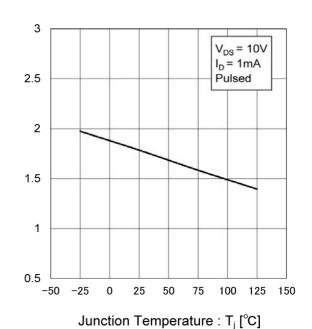
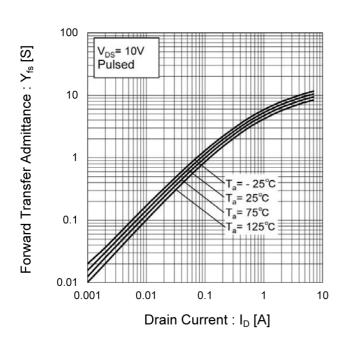


Fig.9 Gate Threshold Voltage vs.
Junction Temperature



Gate Threshold Voltage: VGS(th) [V]

Fig.10 Forward Transfer Admittance vs.
Drain Current



ROHM

6/11

Fig.11 Drain Current Derating Curve

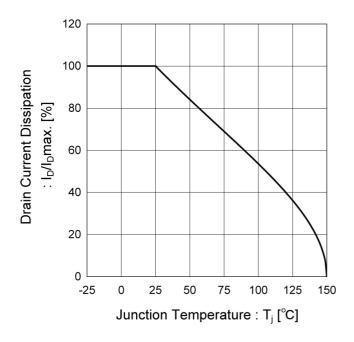


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

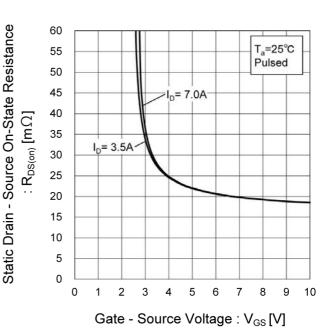


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

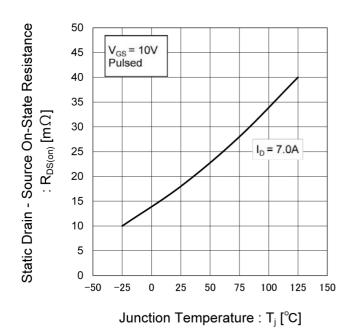


Fig.14 Static Drain - Source On - State
Resistance vs. Drain Current (I)

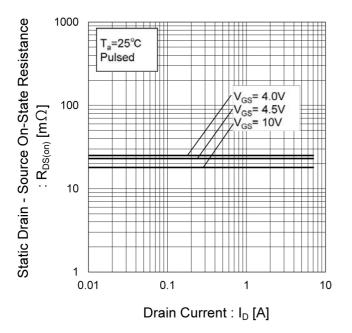


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

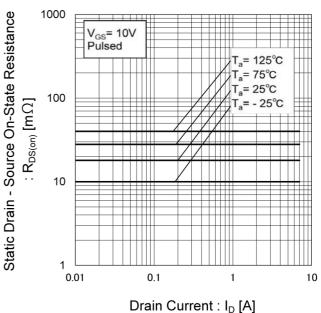


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

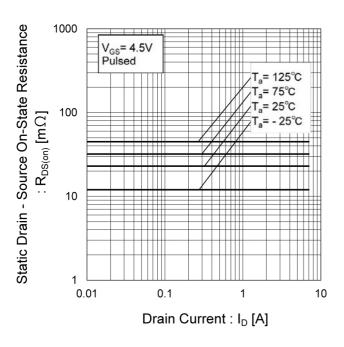


Fig.17 Static Drain - Source On - State Resistance vs. Drain Current (IV)

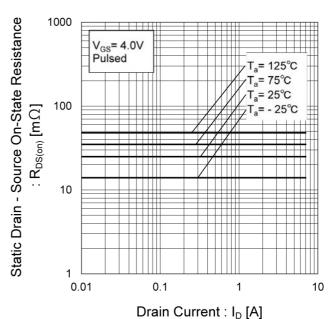


Fig.18 Typical Capacitance vs.

Drain - Source Voltage

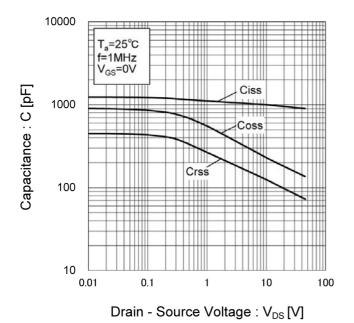


Fig.19 Switching Characteristics

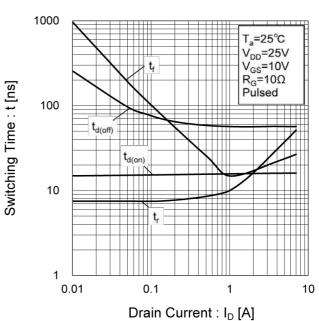


Fig.20 Dynamic Input Characteristics

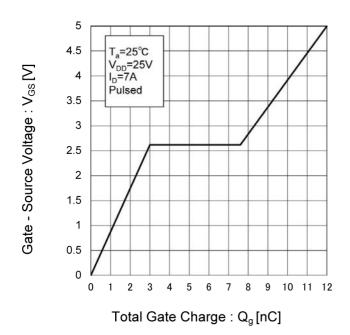
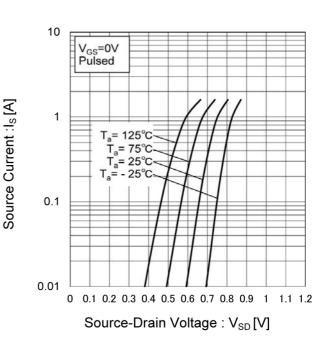


Fig.21 Source Current vs.

Source Drain Voltage



Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

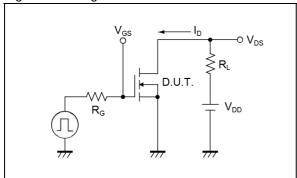


Fig.2-1 Gate Charge Measurement Circuit

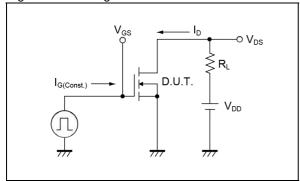


Fig.1-2 Switching Waveforms

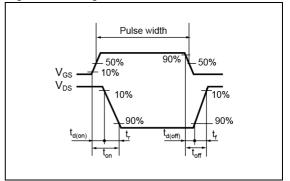
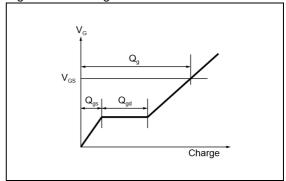
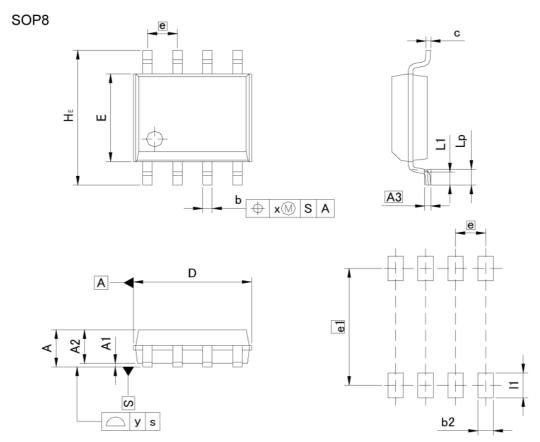


Fig.2-2 Gate Charge Waveform



Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

D114	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	<u>₽3</u>	1.75	=	0.069
A1	0.	15	0.0	006
A2	1.40	1.60	0.055	0.063
A3	0.	25	0.0	10
b	0.30	0.50	0.012	0.020
С	0.10	0.30	0.004	0.012
D	4.80	5.20	0.189	0.205
E	3.75	4.05	0.148	0.159
е	1.27		0.0	50
HE	5.70	6.30	0.224	0.248
L1	0.40	0.60	0.016	0.024
Lp	0.65	0.85	0.026	0.033
х	0.15		0.0	006
у	0.	0.10		004
D.114	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
b2	 2	0.65		0.026
e1	5	15	0.203	

Dimension in mm/inches

e1



0.045

1.15

Notice

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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CLASSIII
CLASSIV	CLASSIII	CLASSIII	CLASSIII

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 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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Notice-PGA-E Rev.003

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